

Thermoelectric Module



Scope

This specification is applied to multicomp thermoelectric modules
Revision of these specifications is carried out after consent

Specifications

Parameters		Remarks
Internal resistance	5 Ω \pm 10%	Note-1
I max.	2.8 A	Note-2
V max.	15.7 V	Note-3
-	Th = 27°C Th = 50°C	-
Q max.	8.7 W 9.6 W	Note-4
Δ T max.	95°C 105°C	Note-5
Solder melting point	138°C	Note-6
Maximum compress	98.07 N / cm ² (10 kgf / cm ²)	Note-7

Note-1 : Measured by AC 4 - terminal method at 25°C

Note-2 : Maximum current at Δ T max.

Note-3 : Maximum voltage at Δ T max.

Note-4 : Maximum cooling capacity at I max. V max. and Δ T = 0°C

Note-5 : Maximum temperature difference at I max. V max. and Q = 0 W

(Maximum parameters are measured in a vacuum 1.3 P)

Note-6 : The solder melting point of thermoelectric module

Note-7 : Recommended maximum compression (not destruction limit)

Specification Table Thot = 27°C

I max. (A)	U max. (V)	Qc max. W	dT max. °C	A	B	H	Part Number
2.8	-	8.7	95	40	40	7	MCPK2-15828NC-S

Dimensions : Millimetres

PK2 Modules are high performance double stage modules, silicone sealed for moisture protection, for applications where high cooling capacity is needed at high operation temperature

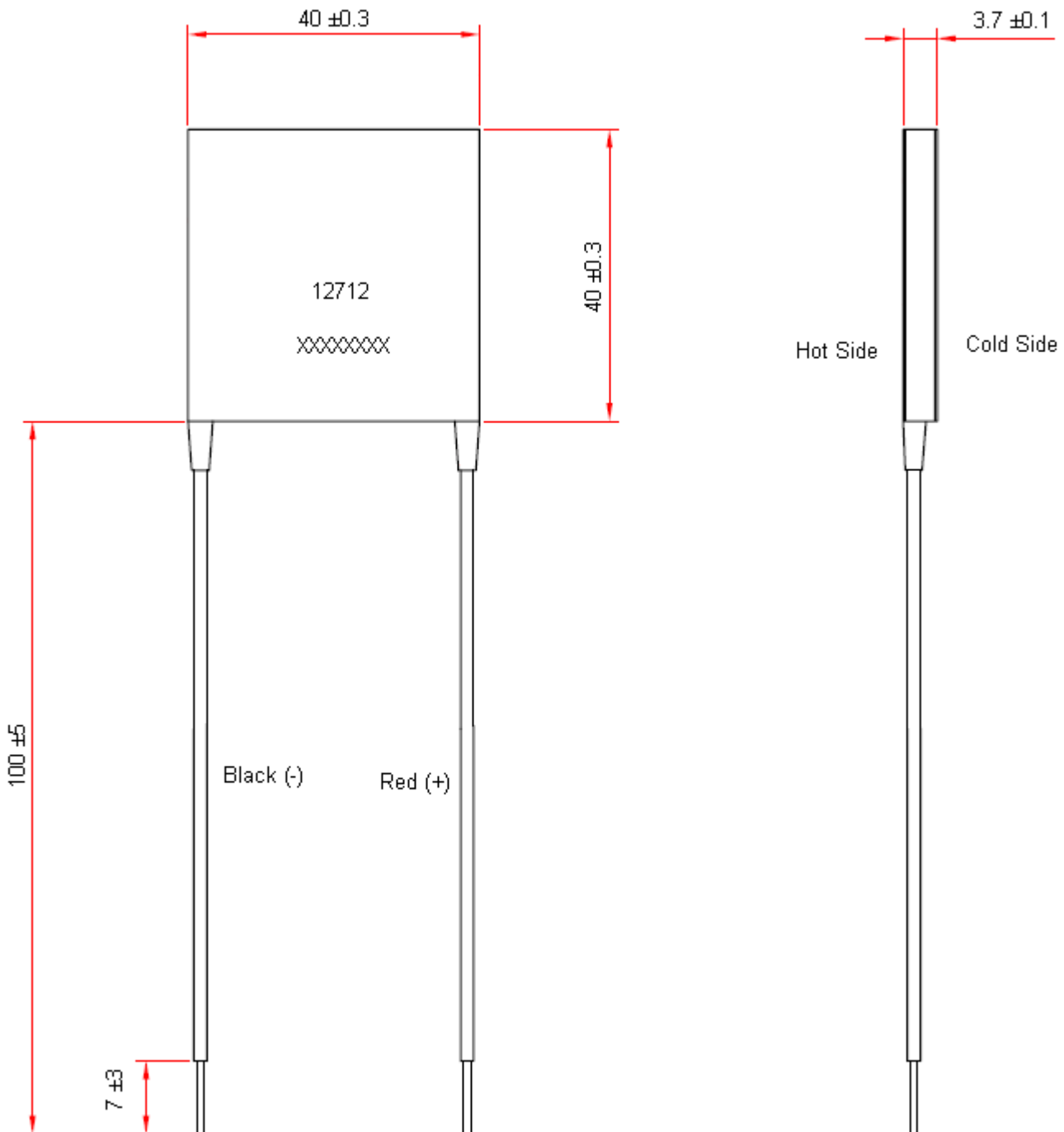
Recommended operation temperature up to 90°C for long life

Recommended operating current 0.7 I max. for long life

Thermoelectric Module



Outline Drawing



Dimensions : Millimetres

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